

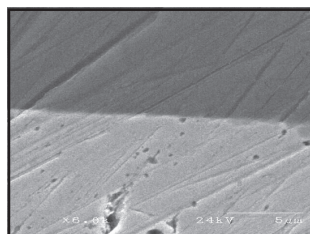
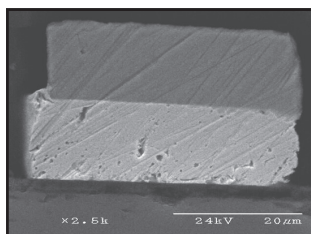
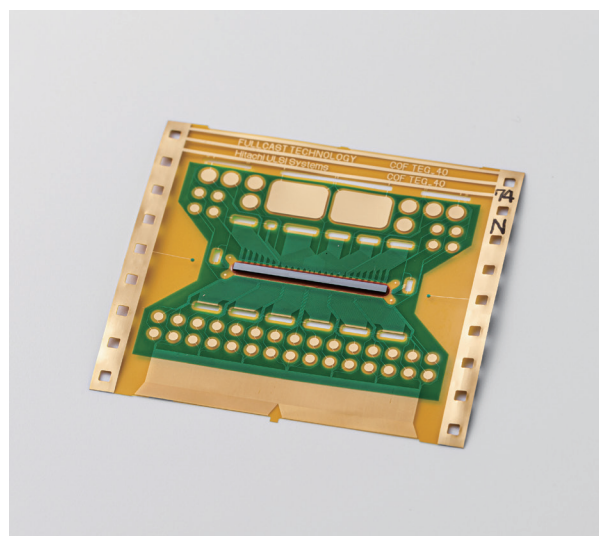
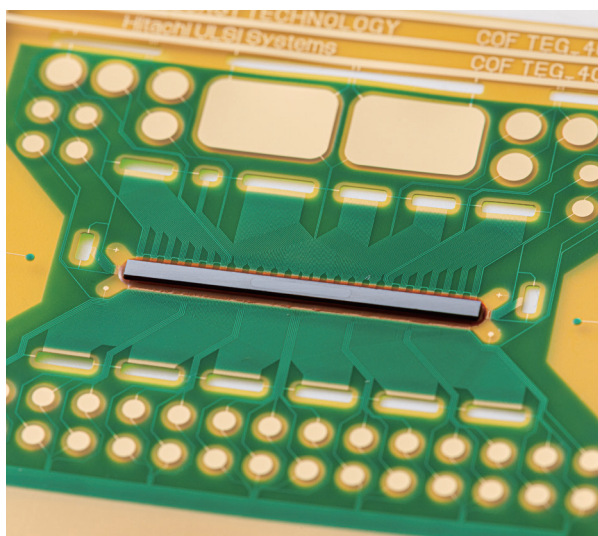


Application

Bonding ボンディング

フリップチップ接合

半導体／多バンプ電極音波接合



(Magnified bonded cross section)

Chip size: 20.05×1.06×0.42 mm
Chip bump: Au plated 770 pins
Bump pitch: 40 (30) μm
Substrate: Au plated pads on 2 layers of film

Product used 使用する装置

■ サウンド&ヒートボンダ



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